L Number	Hits	Search Text	DB	Time stamp
1	0	258/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
2	1190	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
3	2761	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
4	3762	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
5	3762	258/685 257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
6	4289	257/685 257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
7	1577	pad and signal and (257/685 257/723)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:33
8	1421	(pad and signal and (257/685 257/723)) and (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:34
9	1414	((pad and signal and (257/685 257/723)) and (package packaging packaged)) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:35

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6	4289	257/685 257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:29
7	1577	pad and signal and (257/685 257/723)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:33
8	1421	(pad and signal and (257/685 257/723)) and (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 21:34